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## PATENT ABSTRACTS OF JAPAN

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**H01L 23/48**(21) Application number: **59264010**(71) Applicant: **TOSHIBA CORP**(22) Date of filing: **14.12.84**(72) Inventor: **ASADA KOJI**(54) **LEAD FRAME FOR SEMICONDUCTOR DEVICE**

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(57) Abstract:

**PURPOSE:** To improve the quality of semiconductor device avoiding the dispersion in bending angles of each lead by a method wherein through holes corresponding to bending part of leads are made in respective multiple leads mounted together with others on the same plane while notches are formed along the lead bending lines on the lead surface separated holding the through holes.

**CONSTITUTION:** Oval through holes 26a, 26b in the longitudinal direction are made in inner leads 24a, 24b corresponding to bending parts of leads 21a, 21b. Besides, notches 27a, 27b are formed in the direction along bending lines A, A' connecting the bending parts of leads 21a, 21b on the surface of inner leads 24a, 24b separated holding the through holes 26a, 26b when said through holes 26a, 26b are made. In other words, when a semiconductor device utilizing the leadframes so far constituted is produced, the leads 21a, 21b may be formed into specified pattern by bending subject to preliminary bending process along the respective bending lines A, A'.

